FAIRCHILD
SEMICONDUCTOR®
The Right Technology for Your Success

PCN# : P232A
Issue Date : Feb. 22, 2013

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

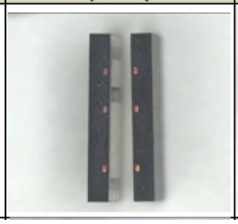
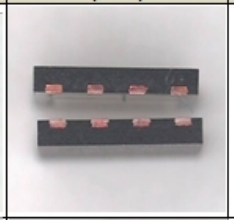
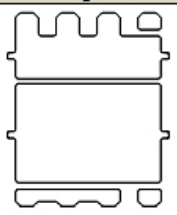
Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : May. 23, 2013

Expected First Date Code of Changed Product :1319

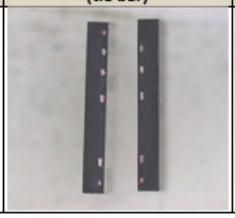
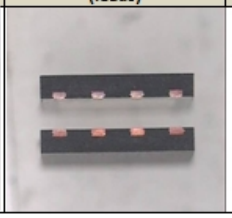
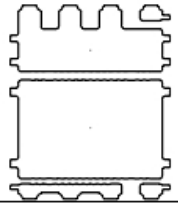
Description of Change (From) :
1) No tie bar connected to the corner leads of the package. Package outline view and diagram as shown in the table below.

Package	Bottom view	Side view (tie bar)	Side view (leads)	Leadframe Diagram
MLP 5X6 8L				

2) 2 mil Au wire bonding.

Description of Change (To) :

1) Added tie bar to the corner leads of the package. Package outline view and diagram as shown in the table below.

Package	Bottom view	Side view (tie bar)	Side view (leads)	Leadframe Diagram
MLP 5X6 8L				

2) Adding 2 mil Cu wire as an alternative wire bonding material.

Reason for Change:
This conversion is to align with Fairchild Penang's consolidation to a similar leadframe process to better utilize equipment. The change will not affect the product electrical specification and solderability. The products incorporating this change may be shipped interchangeably with existing unchanged products. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Affected Product(s):

FDMS9600S	FDMS9620S	FDMS9620S_F106

Qualification Plan	Device	Package	Process	No. of Lots
Q20120109	FDMC9600S	MLDAM_X08 (MLP 5x6 Dual DAP)	PT5 & TB3	2

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/462
MSL1	260C, 3 cycles	**J-STD_020**		0/44
Highly Accelerated Stress Test	130C, 85%RH	**JESD22-A110**	96 hrs	0/154
High Temperature Storage Life	150C	**JESD22-A103**	1000 hrs	0/154
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/154
Bond Pull	9.0g	**JESD22-C100**		0/10
Bond Shear	90g	**AEC-Q100-001**		0/10
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/10
Solderability	Condition C, 245C, 5 Sec	**JESD22-B102D**		0/22
Solderability	Condition C, 215C, 5 Sec	**JESD22-B102D**		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20120109	FDMC9620S	MLDAM_X08 (MLP 5x6 Dual DAP)	PT4 & PT3	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/231
MSL1	260C, 3 cycles	**J-STD_020**		0/22
Highly Accelerated Stress Test	130C, 85%RH	**JESD22-A110**	96 hrs	0/79
High Temperature Storage Life	150C	**JESD22-A103**	1000 hrs	0/79
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/79
Bond Pull	9.0g	**JESD22-C100**		0/5
Bond Shear	90g	**AEC-Q100-001**		0/5
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/5
Solderability	Condition C, 245C, 5 Sec	**JESD22-B102D**		0/11
Solderability	Condition C, 215C, 5 Sec	**JESD22-B102D**		0/11